Abstract of the Disclosure

A wire bonding capillary(1), which is able to decrease wire extraction resistance and suitable for a long and low loop wire bonding process, comprises a through bore(5) for feeding a bonding wire, a funnel-shaped bore(3) for guiding the wire to the through bore, and a tapered portion(11) formed at an exit of the through bore. The through bore length is between 0.2 and 1.5 times the through bore diameter. The tapered portion is tapered in two steps.